

Abstract

An electronic device package comprises a substrate, a die, and a material having a Young's modulus of between about .1 megapascals and about 20 megapascals (at a solder reflow temperature) for attaching the die to the substrate. In one embodiment, the package utilizes a material having a Young's modulus of between about .1 megapascals and about 20 megapascals (at a solder reflow temperature) for attaching the die to the substrate. In an alternate embodiment, the package utilizes a material having a coefficient of thermal expansion α_2 of less than about 400 (four-hundred) ppm (parts per million)/°C for attaching the die to the substrate. In another alternate embodiment, the package utilizes a rigid material for attaching the die to the substrate.

"Express Mail" mailing label number: EL709303688US

Date of Deposit: February 1, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.